

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16271
1.3 Title of PCN	JSCC (China) UFQFPN 4X4 28L new Bill of Material for STM32G051/G061x, STM32C091/C092x, STM32C071x and STM32C051x listed products.
1.4 Product Category	STM32C051x, STM32C071x. STM32C091x, STM32C092x, STM32G051x and STM32G061x.
1.5 Issue date	2026-08-25

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 8946006
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	StatsChipPAC JSCC Jiangyin (China)

4. Description of change

	Old	New
4.1 Description	JSCC (China) UFQFPN 4X4 28L Current Bill Of Material: - Gold wire - Molding compound EME-G770HCD - Leadframe copper, pre-plated	JSCC (China) UFQFPN 4X4 28L new Bill Of Material: - CuPd wire - Molding compound EME-G700LA-LA - Leadframe copper, post-plated
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form is changing as displayed in Additional Information document.	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensure by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2026-08-03
7.2 Intended start of delivery	2026-10-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16271 MDRF-GPAM-RER2507 V3.0 -PCN15803-15804-16271 - JSCC UFQFPN.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-08-25

9. Attachments (additional documentations)
16271 Public product.pdf 16271 MDRF-GPAM-RER2507 V3.0 -PCN15803-15804-16271 - JSCC UFQFPN.pdf 16271 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32C071GBU3TR	
	STM32C071GBU6	
	STM32G051G6U3	
	STM32G051G6U6	
	STM32G051G8U3TR	
	STM32G051G8U6	
	STM32G061G6U6	
	STM32G061G8U6	
	STM32C091GCU3TR	
	STM32G051G8U6TR	
	STM32C051G8U6	

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Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : JSCC (China) UFQFPN 4X4 28L new Bill of Material for STM32G051/G061x, STM32C091/C092x, STM32C071x and STM32C051x listed products.

PCN Reference : EMBEDDED PROCESSING/26/16271

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32G051G6U3TR	STM32C091GCU3	STM32G051G6U3
STM32C092GCU6	STM32C071G8U6TR	STM32G051G8U6TR
STM32C092GCU3TR	STM32G051G8U6	STM32C071GBU3TR
STM32G061G8U6TR	STM32C092GBU6	STM32C051G8U7TR
STM32G061G6U6	STM32C091GBU6	STM32G051G6U6
STM32C071GBU6	STM32G051G8U3TR	STM32C071G8U6
STM32G051G8U3	STM32C051G6U6	STM32C051G8U7
STM32C091GBU7	STM32G061G8U6	STM32C051G8U6TR
STM32C092GCU3	STM32C091GCU3TR	STM32C091GCU6
STM32C071GBU6N	STM32C092GCU7TR	STM32C091GBU7TR
STM32C051G8U6	STM32C071G8U6N	STM32C092GCU7

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PRODUCT/PROCESS CHANGE NOTIFICATION

PCN16271 – Additional information

**JSCC (China) UFQFPN 4X4 28L new Bill of Material for
STM32G051/G061x, STM32C091/C092x, STM32C071x and
STM32C051x listed products.**

**MDRF – General Purpose and Automotive Microcontrollers Division
(GPAM)**

What are the changes?

Changes described in the table below:

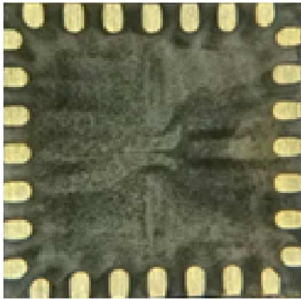
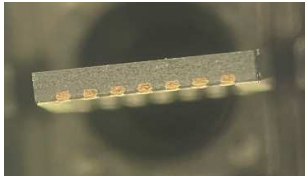
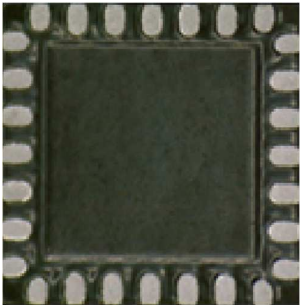
	Existing back-end line	Added back-end line
Assembly site	StatsChipPAC JSCC Jiangyin (China)	
Molding Compound	SUMITOMO EME-G770HCD	SUMITOMO EME-G700LA-LA
Bonding Wire	Gold 0.8Mils	CuPd 0.8Mils
Die Attach	HITACHI DAF HR-5104T-25	HITACHI EN4900GC
Leadframe	Copper, pre-plated	Copper, post-plated
Lead finishing	NiPdAu (e4)	Pure tin (e3)
Solder mask	NA	TAMURA 8000S18 (*)

(*) Change is visible from the bottom of the package

- Half etched QFN with a soldermask at the bottom side
- Leadframe with die pad, making wire bonding process more stable and more robust
- Same POA and same footprint, fully compatible with existing SMD process and PCB layout

How can the change be seen?

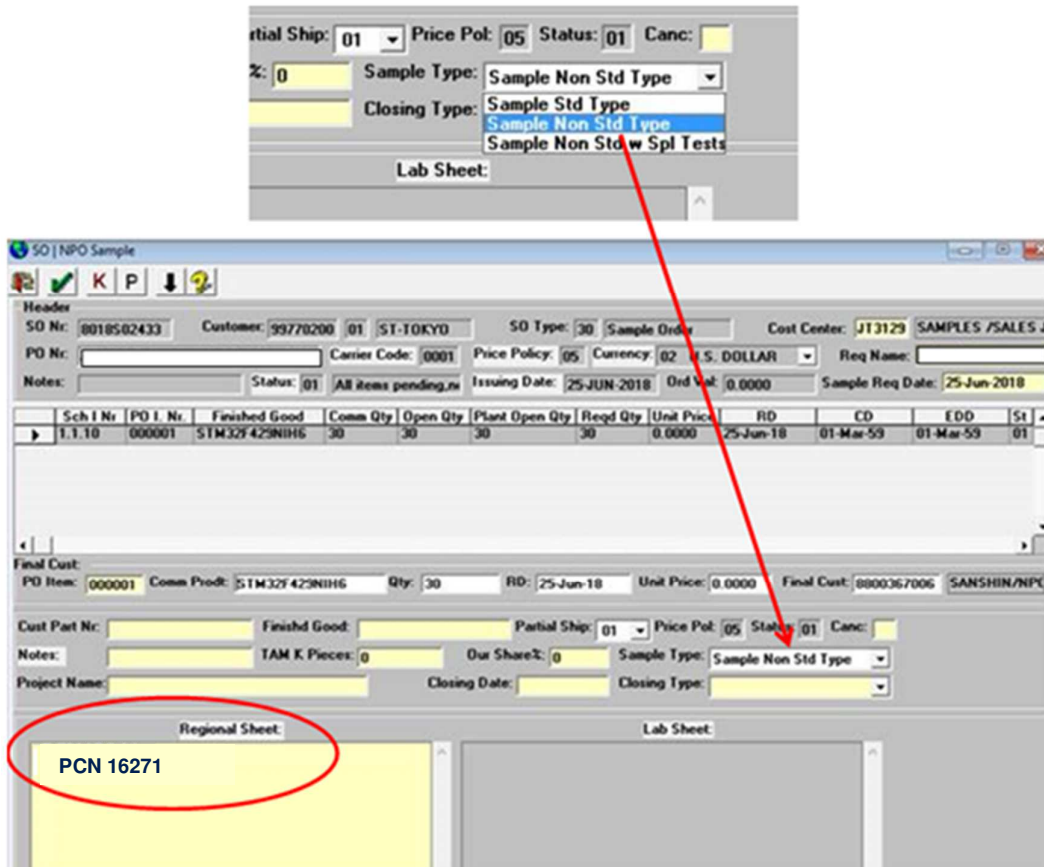
Package top, back and side views:

	Top View	Bottom View	Side View
Existing back-end line			
Added back-end line	Marking is indicative only 		

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu).
- insert the PCN number "**PCN16271**" into the NPO Electronic Sheet/**Regional Sheet**.
- request sample(s) through Notice tool, indicating a single Commercial Product for each request.



The screenshot displays the NPO Sample software interface. At the top, a dropdown menu for 'Sample Type' is open, showing options: 'Sample Std Type', 'Sample Non Std Type' (highlighted), and 'Sample Non Std w Spl Tests'. A red arrow points from this menu to the 'Sample Type' field in the main form. The main form includes fields for 'SO No.', 'Customer', 'SO Type', 'Cost Center', 'PO No.', 'Carrier Code', 'Price Policy', 'Currency', 'Req Name', 'Status', 'Issuing Date', 'Ord Val', and 'Sample Req Date'. Below these is a table with columns: 'Sch I Nr', 'PO I. Nr', 'Finished Good', 'Comm Qty', 'Open Qty', 'Plant Open Qty', 'Reqd Qty', 'Unit Price', 'RD', 'CD', 'EOD', and 'St'. The table contains one row with data. Below the table, there are fields for 'Final Cust', 'PO Item', 'Comm Prod', 'Qty', 'RD', 'Unit Price', and 'Final Cust'. At the bottom, there are fields for 'Cust Part Nr', 'Finishd Good', 'Partial Ship', 'Price Pol', 'Status', 'Canc', 'Notes', 'TAM K Pieces', 'Our Share%', 'Sample Type', 'Closing Date', and 'Closing Type'. The 'Regional Sheet' tab is selected, and the text 'PCN 16271' is entered in the 'Project Name' field, which is circled in red.

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Reliability Evaluation Report

MDRF-GPAM-RER2507

JSCC (China) UFQFPN 4X4 28L - UFQFPN 3X3 20L new Bill of Material for STM32C031x, STM32G071/G081x, STM32G031/G041x, STM32C011x, STM32G051/G061x, STM32C091/C092x, STM32C071x and STM32C051x listed products and additional source.

PCN15803 – PCN15804 – PCN16271

General Information	
Commercial Product	STM32G031G6U6, STM32C031G6U6, STM32C011F6U6
Product Line	466X66,453X66, 443X66
Die revision	466 cut1.2, 453 cut1.1, 443 cut1.1
Product Description	STM32G03x STM32C03x STM32C01X
Package	UFQFPN28 4X4X0.6 P0.5 NO EXP PAD UFQFPN20 3X3X0.6 P0.5 NO EXP PAD
Silicon Technology	TN090CE
Division	MDRF-GPAM

Traceability	
Diffusion Plant	Crolles 300 12, TSMC Fab14 DIFF
Assembly Plant	SC-StatsChippac-China (JSCC)

Reliability Assessment	
Pass	X
Fail	

Release	Date	Author	Function
1.0	09/02/2026	Gabin BOSCO	GPAM BE Q&R
2.0	26/05/2026	Céline NAVARRO	GPAM BE Q&R
3.0	08/07/2026	Gabin BOSCO	GPAM BE Q&R

Approved by:

Approval list V1.0			
Name	Function	Location	Date
Berengere ROUTIER-SCAPPUCCI	GPAM BE Q&R Manager	ROUSSET	9/02/2026
Pascal NARCHE	Subgroup Quality Manager	ROUSSET	10/02/2026
Approval list V2.0			
Name	Function	Location	Date
Berengere ROUTIER-SCAPPUCCI	GPAM BE Q&R Manager	ROUSSET	08/06/2026
Approval list V3.0			
Name	Function	Location	Date
Berengere ROUTIER-SCAPPUCCI	GPAM BE Q&R Manager	ROUSSET	16/07/2026

This report is a summary of the reliability trials performed in good faith by STMicroelectronics. This report does not imply for STMicroelectronics expressly or implicitly any contractual obligations other than as set forth in STMicroelectronics General Terms and Conditions of Sale.

RELIABILITY EVALUATION OVERVIEW

• OBJECTIVE

The aim of this report is to present the reliability evaluation performed for the qualification of JSCC (China) UFQFPN28 4X4 with LF HFBP 4x4 and UFQFPN20 3X3 with LF HFBP 3X3 copper wires on N90 TSMC/Crolles/Agrate.

PCN15803 changes are described below:

	Existing back-end line	Added back-end line
Assembly site	StatsChipPAC JSCC Jiangyin (China)	
Molding Compound	SUMITOMO EME-G770HCD	SUMITOMO EME-G700LA-LA
Bonding Wire	Gold 0.8Mils	CuPd 0.8Mils
Die Attach	HITACHI DAF HR-5104T-25	HITACHI EN4900GC
Leadframe	Copper, pre-plated	Copper, post-plated
Lead finishing	NiPdAu (e4)	Pure tin (e3)
Solder mask	NA	TAMURA 8000S18 (*)

(*) Change is visible from the bottom of the package

- Half etched QFN with a soldermask at the bottom side
- Leadframe with die pad, making wire bonding process more stable and more robust
- Same POA and same footprint, fully compatible with existing SMD process and PCB layout

PCN15804 changes are described below:

	Existing back-end line	Added back-end line
Assembly site	Amkor ATP (Philippines)	StatsChipPAC JSCC Jiangyin (China)
Molding Compound	SUMITOMO EME-G700Y	SUMITOMO EME-G700LA-LA
Bonding Wire	Gold 0.8Mils	CuPd 0.8Mils
Die Attach	DAF Ablestik ATB F125E	DAF Ablestik ATB F125E2
Leadframe	Copper, pre-plated	Copper, post-plated
Lead finishing	NiPdAu (e4)	Pure tin (e3)
Solder mask	NA	TAMURA 8000S18 (*)

(*) Change is visible from the bottom of the package

- Half etched QFN with a soldermask at the bottom side
- Leadframe with die pad, making wire bonding process more stable and more robust
- Same POA and same footprint, fully compatible with existing SMD process and PCB layout

Reliability Evaluation Report

PCN16271 changes are described below:

	Existing back-end line	Added back-end line
Assembly site	StatsChipPAC JSCC Jiangyin (China)	
Molding Compound	SUMITOMO EME-G770HCD	SUMITOMO EME-G700LA-LA
Bonding Wire	Gold 0.8Mils	CuPd 0.8Mils
Die Attach	HITACHI DAF HR-5104T-25	HITACHI EN4900GC
Leadframe	Copper, pre-plated	Copper, post-plated
Lead finishing	NiPdAu (e4)	Pure tin (e3)
Solder mask	NA	TAMURA 8000S18 (*)

(*) Change is visible from the bottom of the package

- Half etched QFN with a soldermask at the bottom side
- Leadframe with die pad, making wire bonding process more stable and more robust
- Same POA and same footprint, fully compatible with existing SMD process and PCB layout

• CONCLUSION

All reliability tests have been completed with positive results for UFQFPN28 4X4, and UFQFPN20 3X3 copper without exposed pad packages. Neither functional nor parametric rejects were detected at final electrical testing.

Package oriented tests have not put in evidence any criticality. Physical analysis performed on samples submitted to tests has not put in evidence any issue. ESD CDM are in accordance with ST spec.

According to good reliability tests results in line with validated product mission profile and reliability strategy, the qualification is granted for products STM32C031x, STM32G071/G081x, STM32G031/G041x, STM32C011x, STM32G051/G061x, STM32C091/C092x, STM32C071x and STM32C051x with N90 technology diffused at TSMC/Crolles/Agrate in UFQFPN28L 4x4 and UFQFPN20 3X3 without exposed pad at JSCC (China) in copper wire assembly line.

Refer to Section 3.0 for reliability test results.

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1. RELIABILITY STRATEGY

Reliability trials performed as part of this reliability evaluation are in agreement with ST 0061692 specification, in full compliancy with the JESD-47 international standard.

For qualification of UFQFPN4x4 28L line with copper wires, reliability was performed on 3 lots from representative test vehicles of STM32C031x, STM32G071/G081x and STM32G031/G041x in N90 TSMC and N90 Crolles technology.

As Crolles 300 and Agrate 300 share same FE manufacturing process and same technology structure N90, Agrate is qualified by similarity.

For qualification of UFQFPN20 3X3 line with copper wires, reliability was performed on 3 lots from representative test vehicles of STM32C011x in N90 TSMC technology.

STM32G051/G061x, STM32C091/C092x, STM32C071x and STM32C051x are qualified by similarity with same technologies qualified on QFN3x3 and QFN4x4 with same BOM.

For details on test conditions, generic data used and specifications references, refer to test results summary in section 3.

2. PRODUCT OR TEST VEHICLE CHARACTERISTICS

2.1. Generalities

Package line	Device (partial Rawline Code)	Diffusion list	Number of lots
UFQFPN20 3X3X0.6	60E4*443QCXZ	TSMC Fab14	3
UFQFPN28 4X4X0.6	60MB*466QCX3	Crolles 300	2
	60MB*453QCXZ	TSMC Fab14	1

2.2. Traceability

2.2.1. Wafer Fab Information

Die 466

Wafer Fab Information		
FAB1		
Wafer fab name / location	Crolles 300	
Wafer diameter (inches)	12	
Wafer thickness (µm)	775±25	
Silicon process technology	TN090CE	
Number of masks	45	
Die finishing front side (passivation) materials	PSG + NITRIDE	
Die finishing back side Materials	RAW SILICON	
Die area (Stepping die size)	4.0921 mm ² (1889.6, 2165.6)	
Die pad size	Geometry	Open(X,Y)

Reliability Evaluation Report

	Rectangular	65,59 μm	
	Rectangular	123,59 μm	
Sawing street width (X,Y) (μm)	80,80		
Metal levels/Materials/Thicknesses	Wire bond pad metal	Composition	Thickness
	1	Ta/Tan/Cu	0.24 μm
	2	Ta/Tan/Cu	0.33 μm
	3	Ta/Tan/Cu	0.33 μm
	4	Ta/Tan/Cu	0.33 μm
	5	Ta/Tan/Cu	0.33 μm
	6	Ta/Tan/Cu	0.90 μm
	7	TaN/Ta/Ti/AlCu	1.45 μm

Die 453

Wafer Fab Information			
FAB1			
Wafer fab name / location	TSMC Taiwan / TSMC Fab14 DIFF		
Wafer diameter (inches)	12		
Wafer thickness (µm)	775±25		
Silicon process technology	TN090CE		
Number of masks	40		
Die finishing front side (passivation) materials	USG+NITRIDE		
Die finishing back side Materials	RAW SILICON		
Die area (Stepping die size)	2.9449 mm² (1419.8, 2074.2)		
Die pad size	Geometry	Open(X,Y)	
	Rectangular	123,59 µm	
Sawing street width (X,Y) (µm)	80,80		
Metal levels/Materials/Thicknesses	Wire bond pad metal	Composition	Thickness
	1	TaN/Ta/CuSeed/Cu	0.24 µm
	2	TaN/Ta/CuSeed/Cu	0.31 µm
	3	TaN/Ta/CuSeed/Cu	0.31 µm
	4	TaN/Ta/CuSeed/Cu	0.31 µm
	5	TaN/Ta/CuSeed/Cu	0.31 µm
	6	TaN/Ta/CuSeed/Cu	0.85 µm
	7	AlCu	1.45 µm

Die 443

Reliability Evaluation Report

Wafer Fab Information			
FAB1			
Wafer fab name / location	TSMC Taiwan / TSMC Fab14 DIFF		
Wafer diameter (inches)	12		
Wafer thickness (μm)	775±25		
Silicon process technology	TN090CE		
Number of masks	40		
Die finishing front side (passivation) materials	USG+NITRIDE		
Die finishing back side Materials	RAW SILICON		
Die area (Stepping die size)	2.4851 mm ² (1727.2, 1438.8)		
Die pad size	Geometry		Open(X,Y)
	Rectangular		59,65 μm
	Rectangular		123,59 μm
Sawing street width (X,Y) (μm)	80,80		
Metal levels/Materials/Thicknesses	Wire bond pad metal	Composition	Thickness
	1	TaN/Ta/CuSeed/Cu	0.24 μm
	2	TaN/Ta/CuSeed/Cu	0.31 μm
	3	TaN/Ta/CuSeed/Cu	0.31 μm
	4	TaN/Ta/CuSeed/Cu	0.31 μm
	5	TaN/Ta/CuSeed/Cu	0.31 μm
	6	TaN/Ta/CuSeed/Cu	0.85 μm
	7	AlCu	1.45 μm

2.2.2.Assembly Information

Assembly Information	
Package 1: UFQFPN28 4X4X0.6 P0.5 NO EXP PAD	
Assembly plant name / location	SC-StatsChippac-China (JSCC)
Pitch (mm)	0.5
Die thickness after back-grinding (µm)	150±25
Die sawing method	Laser groove + mechanical sawing
Bill of Material elements	
Lead frame/material/reference	LF HFBP 4x4 28L 2.9x2.9 Pure tin
Lead frame finishing (material)	Pure Tin (e3): Sn
Die attach material/glue/supplier	HITACHI EN4900GC
Wire bonding material/diameter	CuPd 0.8 mil
Molding compound material/supplier/reference	SUMITOMO G700LALA
Package Moisture Sensitivity Level (JEDEC J-STD020D)	3

Assembly Information	
Package 2: UFQFPN20 3X3X0.6 P0.5 NO EXP PAD	
Assembly plant name / location	SC-StatsChippac-China (JSCC)
Pitch (mm)	0.5
Die thickness after back-grinding (µm)	150±25
Die sawing method	Laser groove + mechanical sawing
Bill of Material elements	
Lead frame/material/reference	LF HFBP 3x3 20L COL Pure tin
Lead frame finishing (material)	Pure Tin (e3): Sn
Die attach material/film/supplier	DAF ABLESTIK ATB F125E2
Wire bonding material/diameter	CuPd 0.8 mil
Molding compound material/supplier/reference	SUMITOMO G700LALA
Package Moisture Sensitivity Level (JEDEC J-STD020D)	3

2.2.3. Reliability testing information

Reliability Testing Information	
Reliability laboratory name / location	Grenoble Rel Lab, Rousset MDG Rel Lab, Shenzhen BE Lab, JSCC Rel Lab, Muar Rel Lab

Note: ST is ISO 9001 certified. This induces certification of all internal and subcontractor labs. ST certification document can be downloaded under the following link: http://www.st.com/content/st_com/en/support/quality-and-reliability/certifications.html

3. TEST RESULTS SUMMARY

3.1. Lot information

Lot #	Diffusion Lot	Die Revision (Cut)	Trace Code	Raw Line	Package
Lot 1	VQ408389	Cut1.2	GQ52728L	60MB*466QCX3	UFQFPN28 4X4X0.6 P0.5 NO EXP PAD
Lot 2	9R450398	Cut1.1	GQ52625K	60MB*453QCXZ	
Lot 3	VQ408389	Cut1.2	GQ52826A	60MB*466QCX3	
Lot 4	9R534266	Cut1.1	GQ5472AD	60E4*443QCXZ	UFQFPN20 3X3X0.6 P0.5 NO EXP PAD
Lot 5	9R534266	Cut1.1	GQ54828S	60E4*443QCXZ	
Lot 6	9R534266	Cut1.1	GQ54828S	60E4*443QCXZ	

3.2. Test results summary

ACCELERATED ENVIRONMENT STRESS TESTS

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
PC	JSTD 020 JESD 22-A113	24h bake@125°C, MSL3 (192h/30°C/60%RH) 3x Reflow simulation Peak Reflow Temp= 260°C	3	231	693	Lot 1: 0/231 Lot 2: 0/231 Lot 3: 0/231 Lot 4: 0/179 Lot 5: 0/179 Lot 6: 0/179	NA
PC	JSTD 020 JESD 22-A113	24h bake@125°C, MSL1 (168h/85°C/85%RH) 3x Reflow simulation Peak Reflow Temp= 260°C	3	179	537	Lot 4: 0/179 Lot 5: 0/179 Lot 6: 0/179	NA
HTSL	JESD22-A103	Ta= 150°C Duration= 1000hrs	6	77	462	Lot 1: 0/77 Lot 2: 0/77 Lot 3: 0/77 Lot 4: 0/77 Lot 5: 0/77 Lot 6: 0/77	NA
TC	JESD22-A104	Ta= -65/150°C Cyc= 500 ☒ After PC	6	77	462	Lot 1: 0/77 Lot 2: 0/77 Lot 3: 0/77 Lot 4: 0/77 Lot 5: 0/77 Lot 6: 0/77	NA
THB	JESD22-A101	Ta=85°C/85%RH VDD=3v6 Duration= 1000hrs ☒ After PC	3	77	231	Lot 1: 0/77 Lot 2: 0/77 Lot 3: 0/77	NA
			3	25	75	Lot 4: 0/25 Lot 5: 0/25 Lot 6: 0/25	

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UHASt	JESD22-A118	Ta=130°C ,85% RH, 2 Atm Duration= 96hrs ☒ After PC	6	77	462	Lot 1: 0/77 Lot 2: 0/77 Lot 3: 0/77 Lot 4: 0/77 Lot 5: 0/77 Lot 6: 0/77	NA
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ELECTRICAL TEST VERIFICATION

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
CDM	JEDEC JS-002	Voltage=500V class C2a	3	3	9	Lot 1: 0/3 Lot 2: 0/3 Lot 4: 0/3	NA

PACKAGE ASSEMBLY INTEGRITY TESTS

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
CA	ST internal specifications JESD 22B102 JESDB100/B108	Construction analysis including Solderability, physical dimension, ball shear and pull test.	4	50	200	Lot 1: 0/50 Lot 2: 0/50 Lot 4: 0/50 Lot 5: 0/50	SHZ - CA_25_00388 NRL202507_0584 MDG Muar_26_00007 MDG Muar_26_00009

Note: Test method revision reference is the one active at the date of reliability trial execution.

4. APPLICABLE AND REFERENCE DOCUMENTS

Reference	Short description
JESD47	Stress-Test-Driven Qualification of Integrated Circuits
SOP2.4.4	Record Management Procedure
SOP2.6.2	Internal Change Management
SOP2.6.7	Finished Good Maturity Management
SOP2.6.9	Package & Process Maturity Management in BE
SOP2.6.11	Program Management for Product Development
SOP2.6.17	Management of Manufacturing Transfers
SOP2.6.19	Front-End Technology Platform Development and Qualification
DMS 0061692	Reliability Tests and Criteria for Product Qualification
JEDEC JS-002	Electrostatic discharge (ESD) sensitivity testing charge device model (CDM)
JESD 22-A103	High Temperature Storage Life
J-STD-020	Moisture/reflow sensitivity classification for non-hermetic solid state surface mount devices
JESD22-A113	Preconditioning of non-hermetic surface mount devices prior to reliability testing
JESD22-A118	Unbiased Highly Accelerated temperature & humidity Stress Test
JESD22-A104	Temperature cycling
JESD22-A101	Temperature Humidity Bias
JESD22-B102	Solderability test
JESD B100/108	Physical dimension

5. GLOSSARY

ESD-CDM	Electrostatic Discharge - Charged device model
CA	Construction analysis
HTSL	High Temperature Storage Life
PC	Preconditioning
TC	Temperature Cycling
THB	Temperature Humidity Bias
UHASt	Unbiased HAST (Highly Accelerated Stress Test)
DMS	ST Advanced Documentation Controlled system/ Documentation Management system

6. REVISION HISTORY

Release	Date	Description
1.0	09/02/2026	Initial Release
2.0	26/05/2026	Added die 443 QFN20 3x3
3.0	08/07/2026	Added PCN 16271

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